



N-Channel 60-V (D-S) Fast Switching MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	$r_{DS(on)}\left(\Omega\right)$	I _D (A)		
60	0.022 at V _{GS} = 10 V	10.3		
	0.031 at V _{GS} = 4.5 V	8.7		

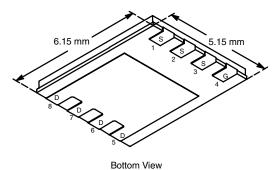
FEATURES

- TrenchFET[®] Power MOSFET
- New Low Thermal Resistance PowerPAK® Package with Low 1.07-mm Profile



- · PWM Optimized for Fast Switching
- 100 % R_a Tested
- Lead (Pb)-free Version is RoHS Compliant

PowerPAK SO-8

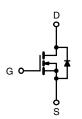


Ordering Information: Si7850DP-T1

Si7850DP-T1—E3 (Lead (Pb)-free)

APPLICATIONS

- Primary Side Switch for 24-V DC/DC Applications
- Secondary Synchronous Rectifier



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T_A	= 25 °C, unles	ss otherwise r	noted		
Parameter		Symbol	10 secs	Steady State	Unit
Drain-Source Voltage		V_{DS}	60		V
Gate-Source Voltage		V_{GS}	± 20		V
Continuous Drain Current (T _{.I} = 150 °C) ^a	T _A = 25 °C	I _D	10.3	6.2	
Continuous Diain Current (1) = 150 °C)	T _A = 85 °C		7.5	4.5	
Continuous Source Current		I _S	3.7	1.5	Α
Pulsed Drain Current		I _{DM}	40		
Avalanche Current ^b		I _{AS}	15		
Single Avalanche Energy ^b		E _{AS}	11		mJ
Maximum Power Dissipation ^a	T _A = 25 °C	P _D	4.5	1.8	W
•	T _A = 85 °C	ט י	2.3	0.9	VV
Operating Junction and Storage Temperature Range		T _J , T _{stg}	– 55 to 150		°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Marrian una luncation de Ameleianda	t ≤ 10 sec	R _{thJA}	22	28	
Maximum Junction-to-Ambient ^a	Steady State		58	70	°C/W
Maximum Junction-to-Case (Drain)	Steady State	R_{thJC}	2.6	3.3	

a. Surface Mounted on 1" x 1" FR4 Board.
b. Guaranteed by design, not subject to production testing.

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply.

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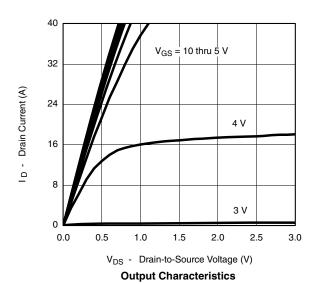


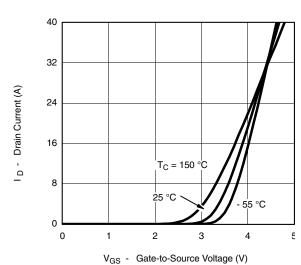
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit	
Static	<u> </u>		1				
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V, } I_D = 250 \mu\text{A}$	60			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1		3	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V			1		
		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			20	μA	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	40			Α	
Drain-Source On-State Resistance ^a		V _{GS} = 10 V, I _D = 10.3 A		0.018	0.022	-	
	r _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 8.7 \text{ A}$		0.025	0.031	Ω	
Forward Transconductance ^a	g _{fs}	$V_{DS} = 15 \text{ V}, I_D = 10.3 \text{ A}$		26		S	
Diode Forward Voltage ^a	V _{SD}	$I_S = 3.8 \text{ A}, V_{GS} = 0 \text{ V}$		0.85	1.2	V	
Dynamic ^b							
Total Gate Charge	Q_g			18	27	nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 10.3 \text{ A}$		3.4			
Gate-Drain Charge	Q _{gd}			5.3		1	
Gate Resistance	R _G		0.5	1.4	2.2	Ω	
Turn-On Delay Time	t _{d(on)}			10	20		
Rise Time	t _r			10	20		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 1 \text{ A}, V_{GEN} = 10 \text{ V}, R_G = 6 \Omega$		25	50	ns	
Fall Time	t _f			12	24		
Source-Drain Reverse Recovery Time	ce-Drain Reverse Recovery Time t _{rr}			50	80		

Notes a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless noted



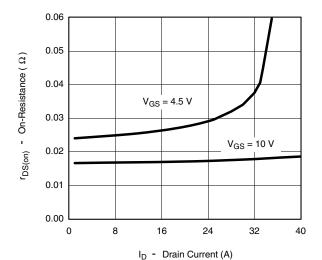




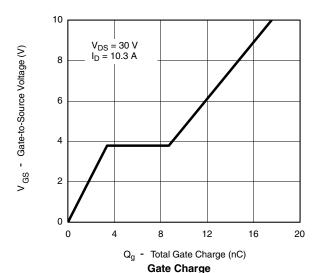


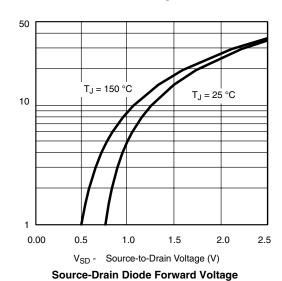


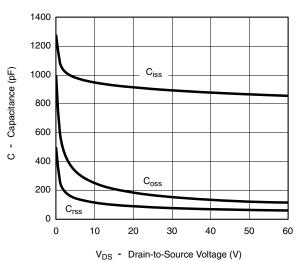
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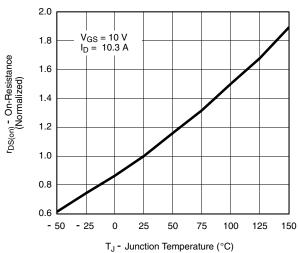
On-Resistance vs. Drain Current



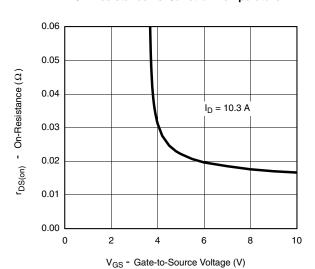




Capacitance



On-Resistance vs. Junction Temperature



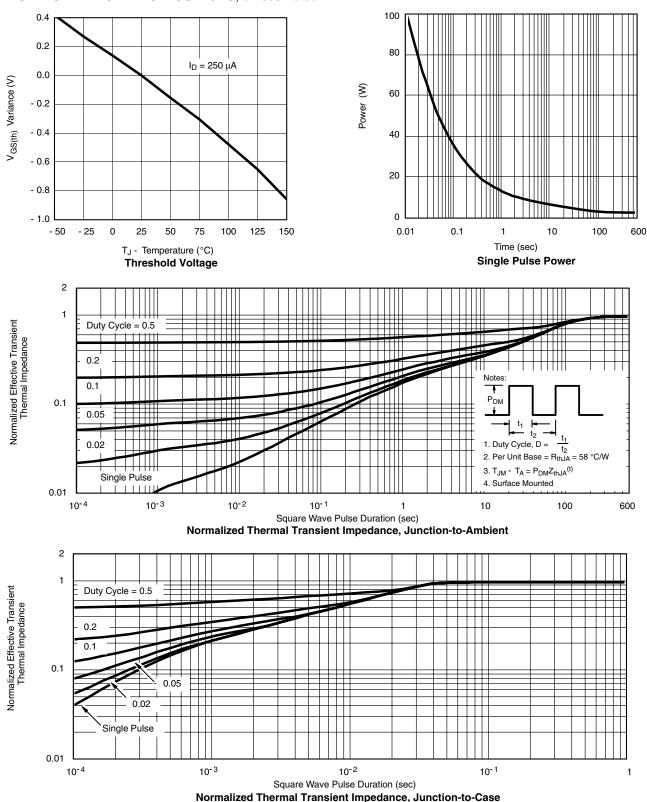
On-Resistance vs. Gate-to-Source Voltage

Is - Source Current (A)

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TYPICAL CHARACTERISTICS 25 °C, unless noted



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